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## FAIRCHILD

SEMICONDUCTOR

#### November 2013

FQP4P40

# **P-Channel QFET® MOSFET**

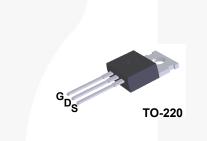
-400 V, -3.5 A, 3.1  $\Omega$ 

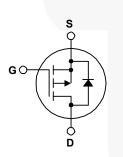
## Description

This P-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state • Low Gate Charge (Typ. 18 nC) resistance, and to provide superior switching performance . Low Crss (Typ. 11 pF) and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, • 100% Avalanche Tested DC motor control, and variable switching power applications.

#### Features

- -3.5 A, -400 V,  $R_{DS(on)}$  = 3.1  $\Omega$  (Max.) @ V<sub>GS</sub> = -10 V, I<sub>D</sub> = -1.75 A





#### Absolute Maximum Ratings T<sub>c</sub> = 25°C unless otherwise noted.

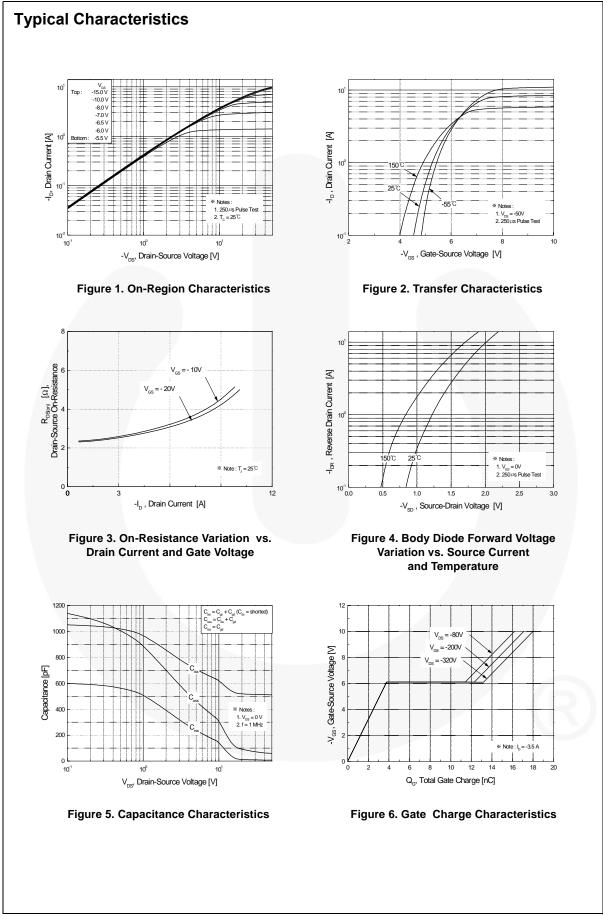
Symbol	Parameter	FQP4P40	Unit		
V <sub>DSS</sub>	Drain-Source Voltage	-400	V		
I <sub>D</sub>	Drain Current - Continuous ( $T_C = 25^{\circ}C$ )		-3.5	А	
	- Continuous (T <sub>C</sub> = 100°C)		-2.2	A	
I <sub>DM</sub>	Drain Current - Pulsed	Note 1)	-14	A	
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy	Note 2)	260	mJ	
I <sub>AR</sub>	Avalanche Current	Note 1)	-3.5	A	
E <sub>AR</sub>	Repetitive Avalanche Energy	Note 1)	8.5	mJ	
dv/dt	Peak Diode Recovery dv/dt	Note 3)	-4.5		
PD	Power Dissipation ( $T_C = 25^{\circ}C$ )		85	W	
	- Derate above 25°C		0.68 V		
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150		
TL	Maximum lead temperature for soldering,	300		°C	
-	1/8" from case for 5 seconds				

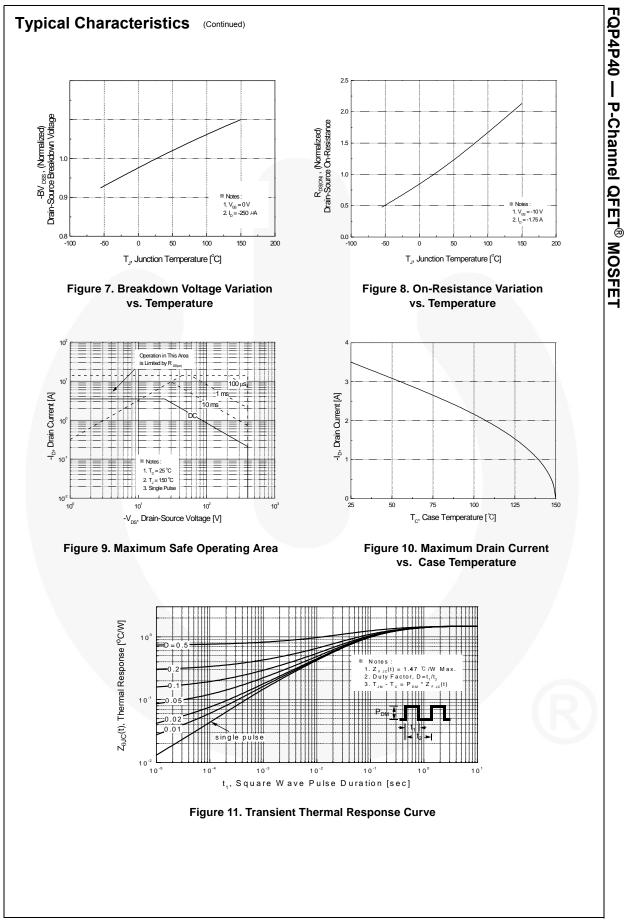
### **Thermal Characteristics**

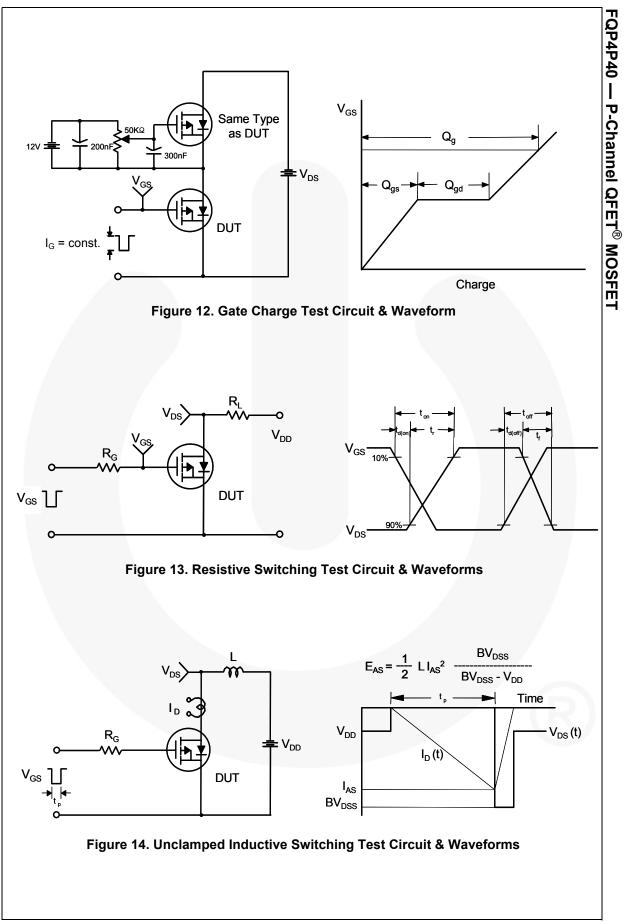
Symbol	Parameter	FQP4P40	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	1.47	°C/W
$R_{\thetaJA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

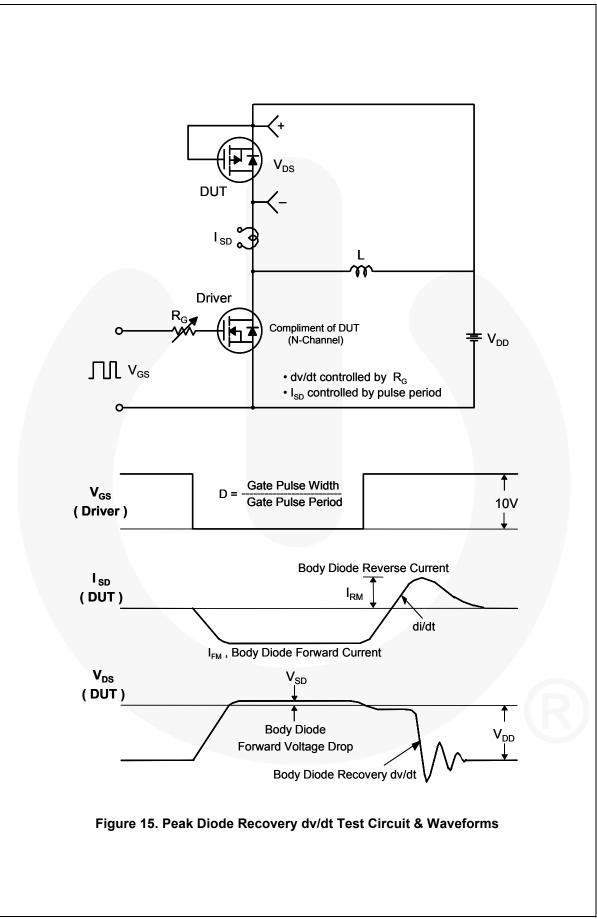
Part NumberTop MarkPackFQP4P40FQP4P40TO-2				Reel	Size	Tape Wi	dth Q	Quantity 50 units	
				N/A	۸	N/A	50		
						<u>.</u>		<u> </u>	
cal Cha	racteristics	T <sub>C</sub> = 25°C	C unless o	therwise noted.			1		1
	Parameter			Test Conditions		Min.	Тур.	Max.	Unit
racterist	ics								
		tage	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = -250 μA		-400			V
Breakdown Voltage Temperature Coefficient		$I_D = -250 \ \mu$ A, Referenced to 25°C			0.36		V/°C		
Zana Cata			V <sub>DS</sub> =	-400 V, V <sub>GS</sub> = 0 V				-1	μA
Zero Gate	e voitage Drain Curi	ent	V <sub>DS</sub> = -320 V, T <sub>C</sub> = 125°C					-10	μA
Gate-Bod	y Leakage Current,	Forward	$V_{GS} = -30 V, V_{DS} = 0 V$ $V_{GS} = 30 V, V_{DS} = 0 V$					-100	nA
Gate-Bod	y Leakage Current,	Reverse						100	nA
ractorict	ice								
		-	V <sub>DS</sub> =	- V <sub>GS</sub> , I <sub>D</sub> = -250 μA		-3.0		-5.0	V
Static Dra	in-Source	_	-				2.44	3.1	Ω
			V <sub>DS</sub> =	-50 V, I <sub>D</sub> = -1.75 A			2.7		S
ic Chara	cteristics								
		_	$V_{DS} = -25 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ f = 1.0 MHz				520	680	pF
Output Ca	apacitance	_				80	105	pF	
	•	e				11	15	pF	
		_					13	35	ns
		_		=					ns
		_	$R_{G} =$	25 Ω					ns
					(Note 4)				ns
			V	-320 V I= -35 A					nC
	, i i i i i i i i i i i i i i i i i i i		-						nC
			•GS -		(Note 4)		9.4		nC
						7	-		/
	Continuous Drain-			ximum Ratings				-3.5	А
IVIAAIIIIUIII								-14	Α
	Pulsed Drain-Sour	oo bioao i							
Maximum	Pulsed Drain-Sour Irce Diode Forward		V <sub>GS</sub> =	= 0 V, I <sub>S</sub> = -3.5 A				-5.0	V
Maximum Drain-Sou				= 0 V, I <sub>S</sub> = -3.5 A = 0 V, I <sub>S</sub> = -3.5 A,			260	-5.0 	V ns
	Drain-Sou Breakdow Coefficien Zero Gate Gate-Bod Gate-Bod Gate-Bod Gate-Bod Con-Resis Forward T C Charac Input Cap Output Ca Reverse T ng Chara Turn-On I Turn-On F Turn-Off I Turn-Off I Turn-Off I Turn-Off I Turn-Off I	racteristics Drain-Source Breakdown Vol Breakdown Voltage Tempera Coefficient Zero Gate Voltage Drain Curr Gate-Body Leakage Current, Gate-Body Leakage Current, Gate-Body Leakage Current, Gate-Body Leakage Current, Gate-Body Leakage Current, Facteristics Gate Threshold Voltage Static Drain-Source On-Resistance Forward Transconductance ic Characteristics Input Capacitance Output Capacitance	aracteristics   Drain-Source Breakdown Voltage   Breakdown Voltage Temperature   Coefficient   Zero Gate Voltage Drain Current   Gate-Body Leakage Current, Forward   Gate-Body Leakage Current, Reverse   racteristics   Gate Threshold Voltage   Static Drain-Source   On-Resistance   Forward Transconductance   ic Characteristics   Input Capacitance   Output Capacitance   Reverse Transfer Capacitance   ng Characteristics   Turn-On Delay Time   Turn-On Rise Time   Turn-Off Fall Time   Total Gate Charge   Gate-Charge	racteristicsDrain-Source Breakdown Voltage $V_{GS}$ =Breakdown Voltage Temperature Coefficient $I_D$ = -2Zero Gate Voltage Drain Current $V_{DS}$ =Gate-Body Leakage Current, Forward $V_{GS}$ =Gate-Body Leakage Current, Reverse $V_{GS}$ =Gate-Body Leakage Current, Reverse $V_{GS}$ =Gate Threshold Voltage $V_{DS}$ =Static Drain-Source On-Resistance $V_{DS}$ =Forward Transconductance $V_{DS}$ =ic Characteristics $V_{DS}$ =Input Capacitance $V_{DS}$ =Output Capacitance $f = 1.0$ Reverse Transfer Capacitance $V_{DD}$ =Turn-On Delay Time Turn-On Rise Time $V_{DD}$ =Turn-Off Fall Time $V_{DS}$ =Turn-Off Fall Time $V_{DS}$ =Gate-Source Charge $V_{DS}$ =	racteristicsDrain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, I_D = -250 \mu \text{A}$ Breakdown Voltage Temperature Coefficient $I_D = -250 \mu \text{A}$ , Referenced toZero Gate Voltage Drain Current $V_{DS} = 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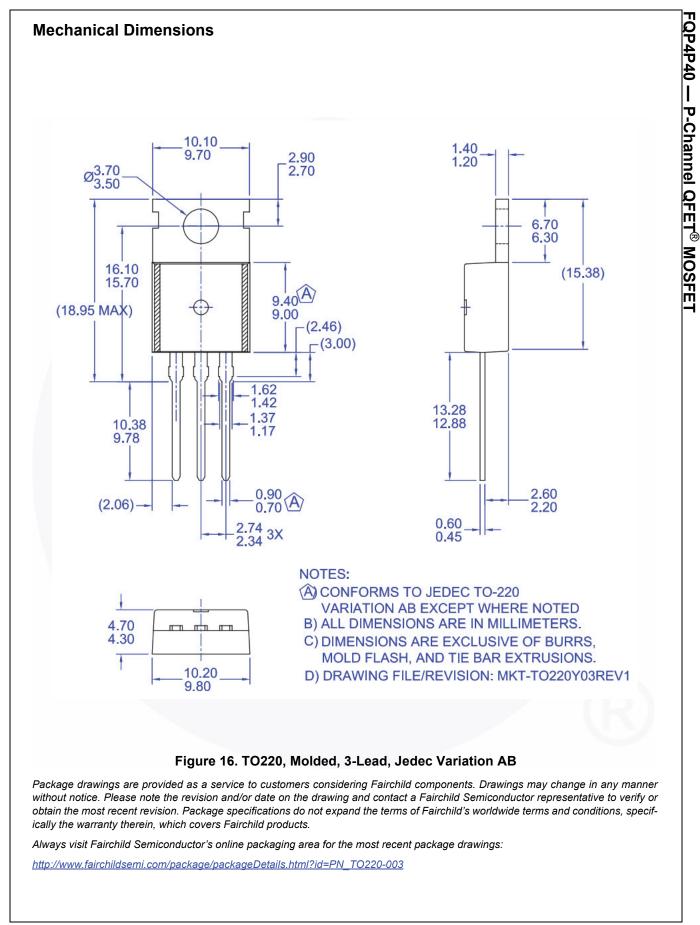
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